

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al.

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Filed.: September 18, 2003

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Examiner: Le, Thao X.

MAY 17 2005

Title: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES

Honorable Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION

*Please  
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05/25/05*

This Request for Reconsideration is being filed in response to the Final Office Action mailed on March 23, 2005. Applicants request this Amendment be entered in the above-identified application and reconsideration of the application in view of the Amendments and Remarks that follow.

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